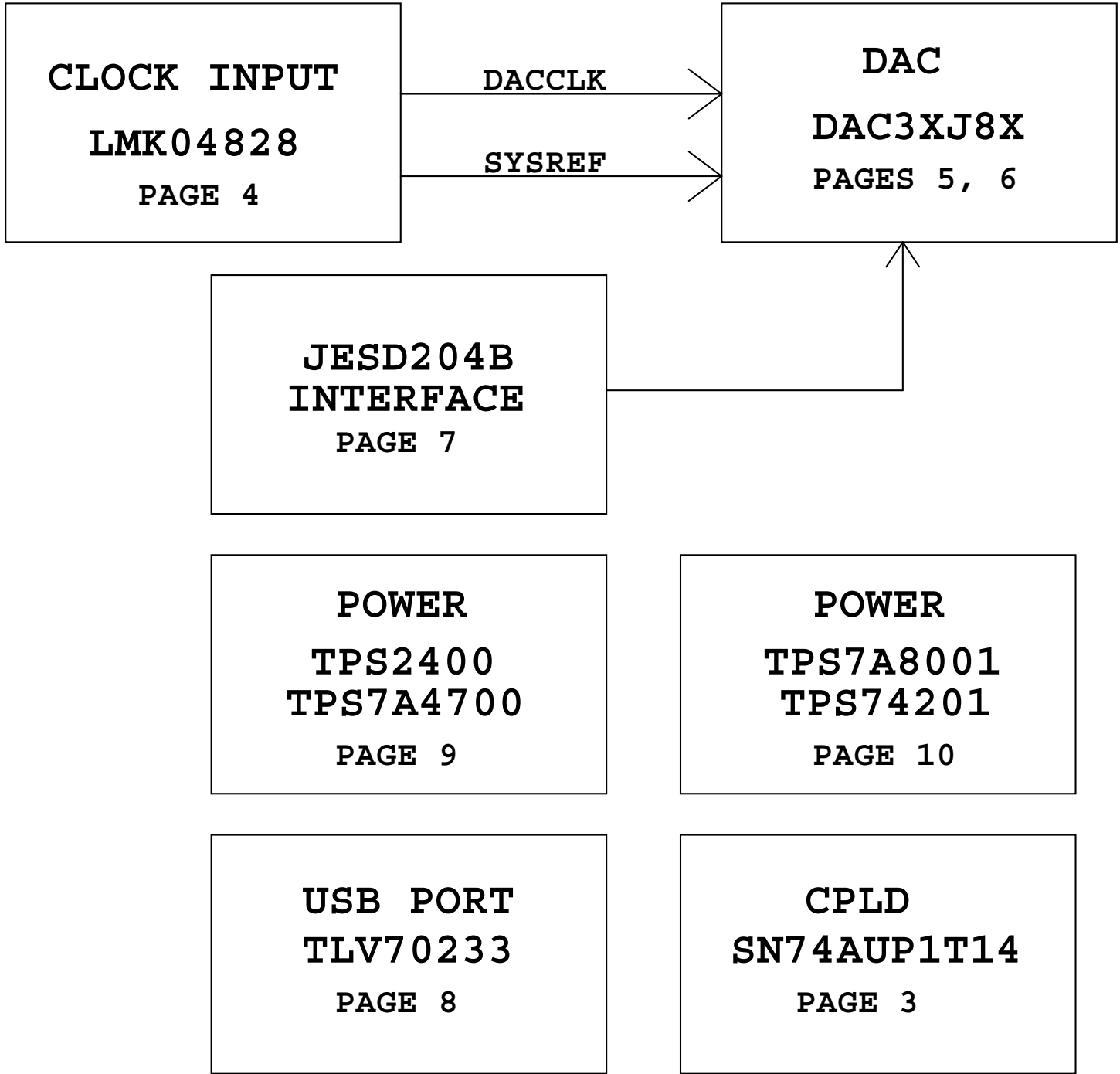



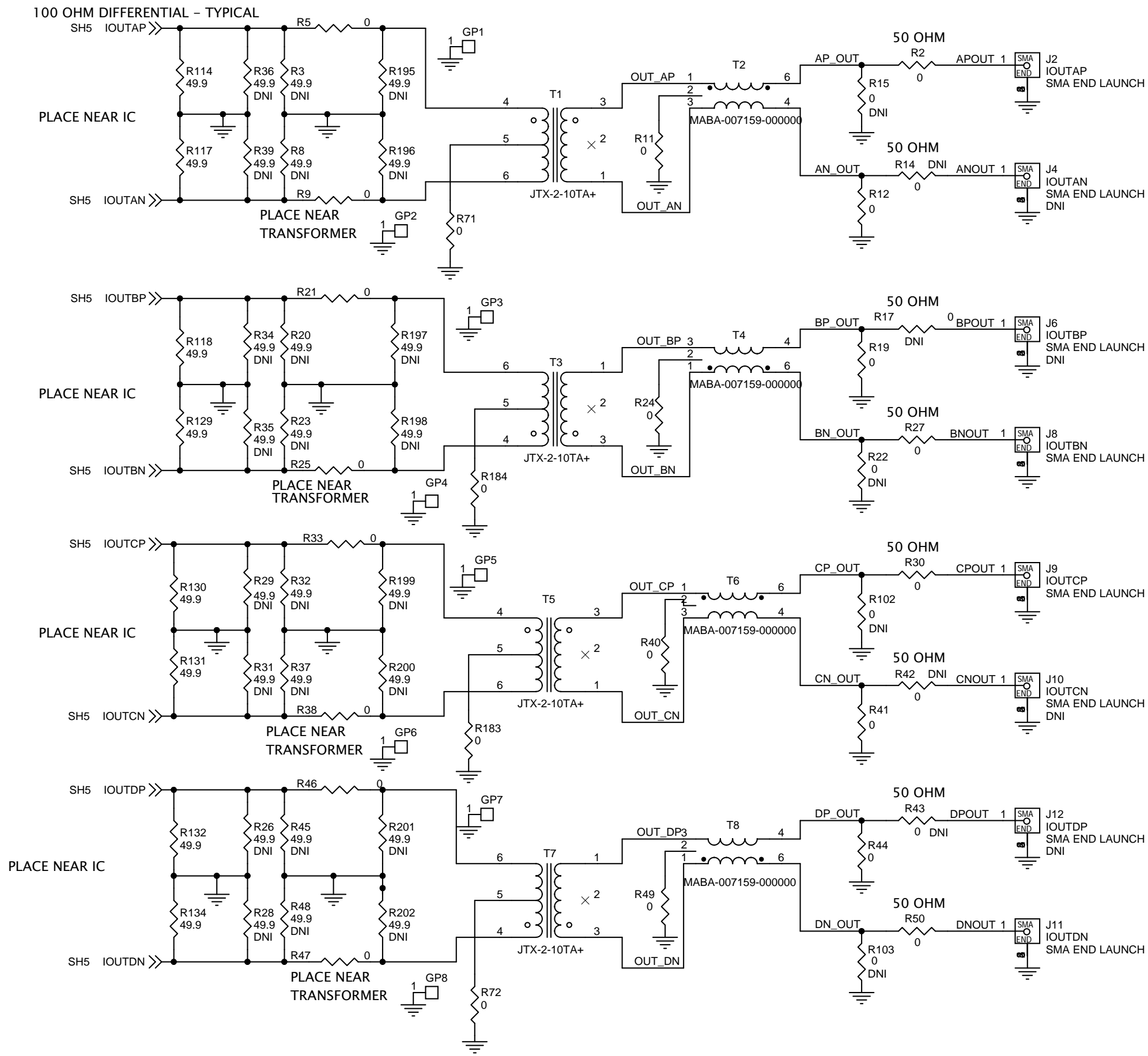
TI Design #: TIDA-00996



 **TEXAS INSTRUMENTS**

Title: **BLOCK DIAGRAM**

Drawn: JV SMITH 02/13	Size <b>B</b>	Document Number <b>DAC3XJ8X EVM</b>	Rev <b>D</b>
Engineer: M GUIBORD 02/13	Date: Friday, November 08, 2013	Sheet 1 of 10	



**NOTES:**  
 1) DNI = DO NOT INSTALL

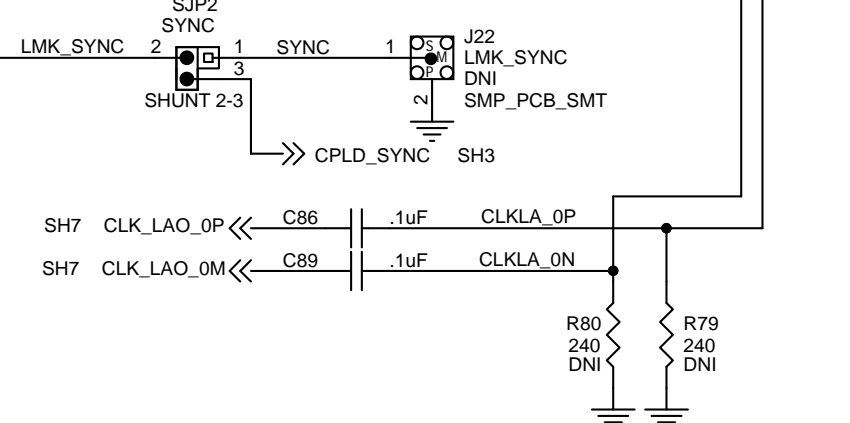
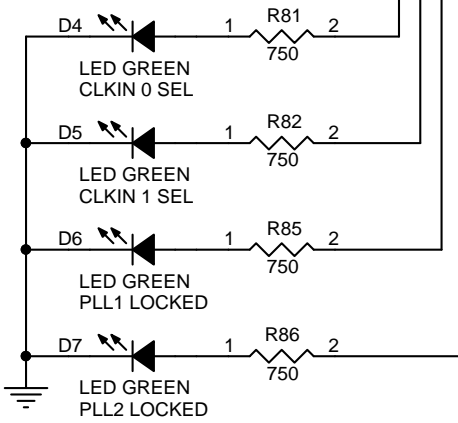
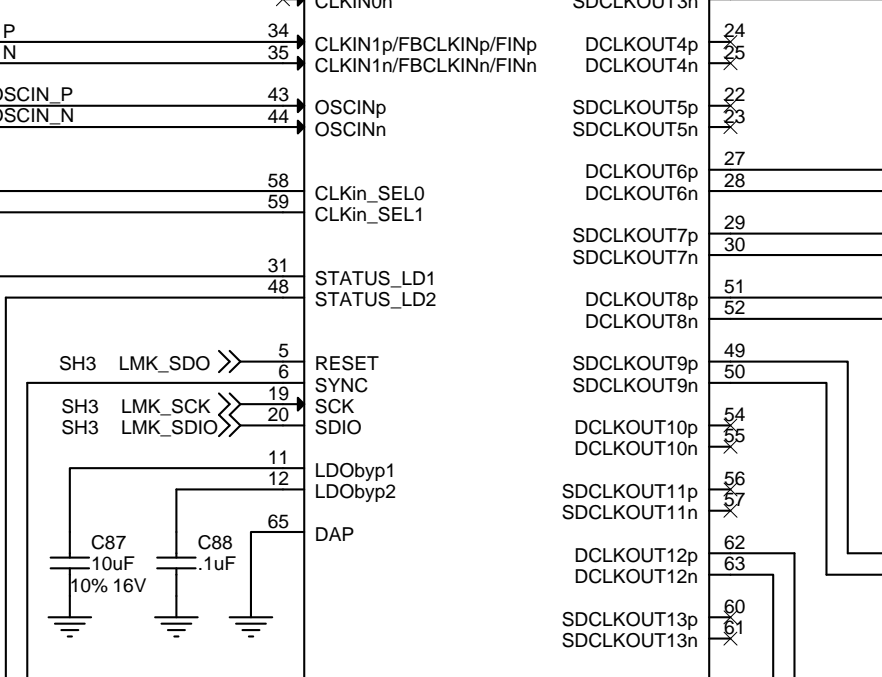
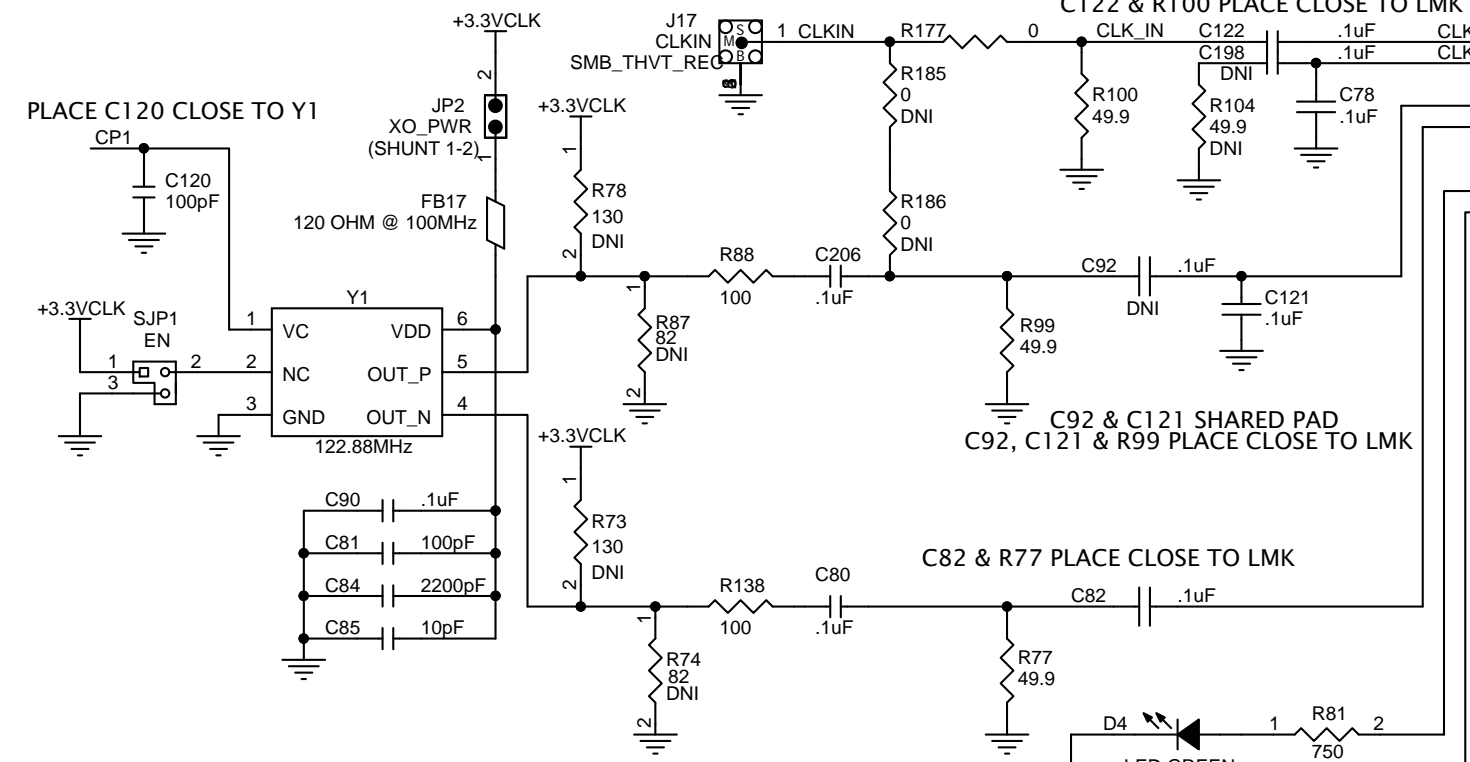
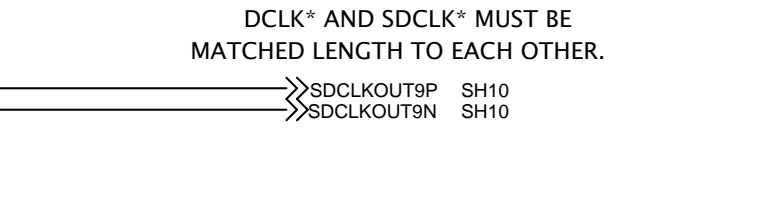
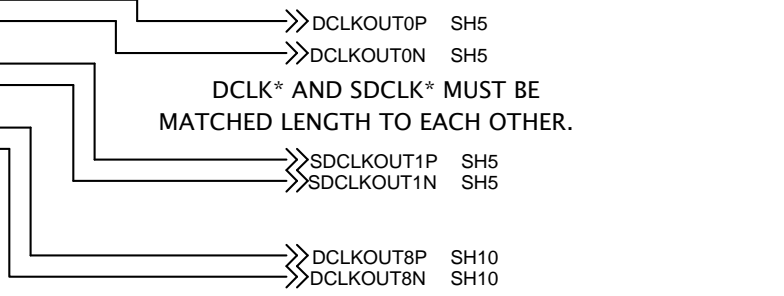
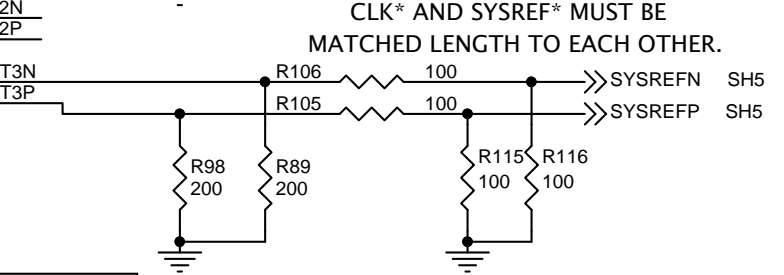
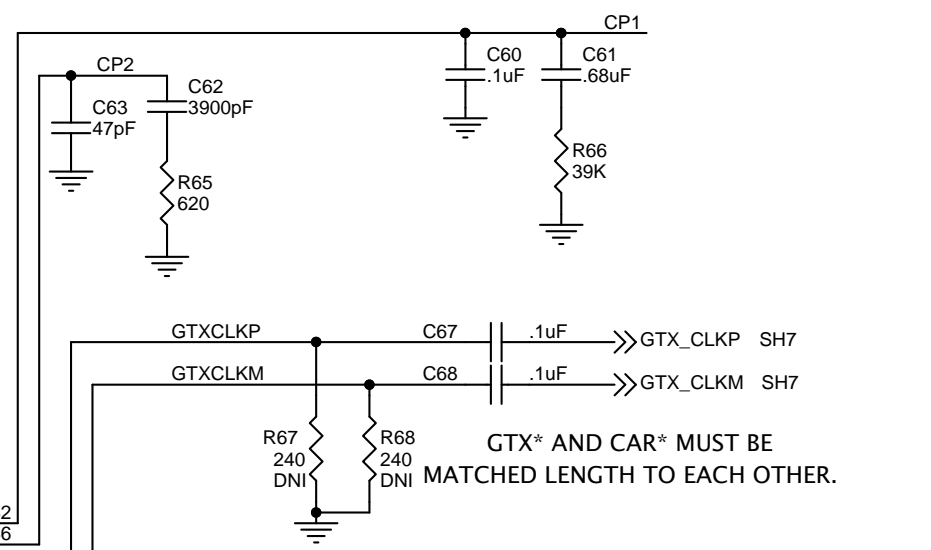
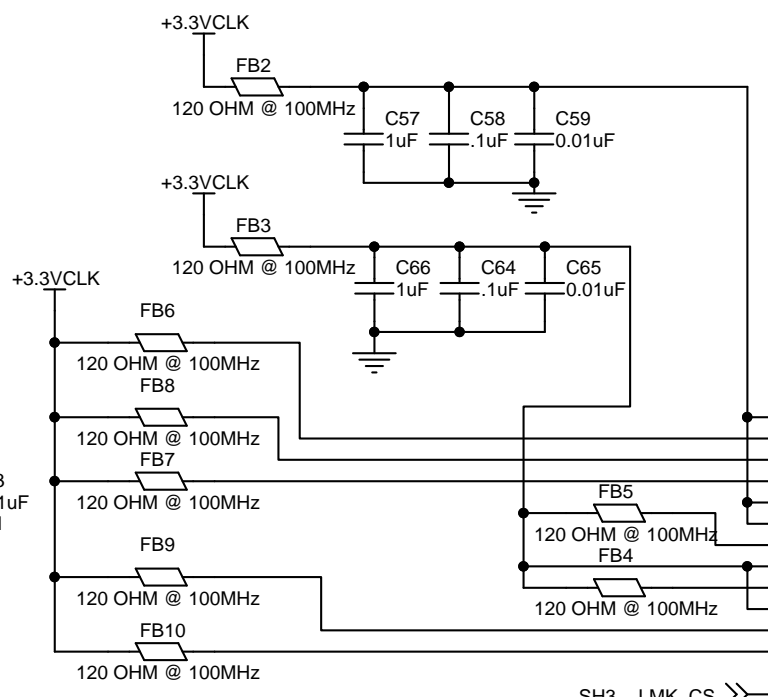
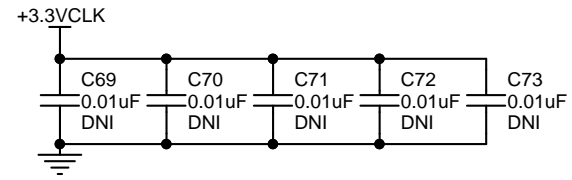
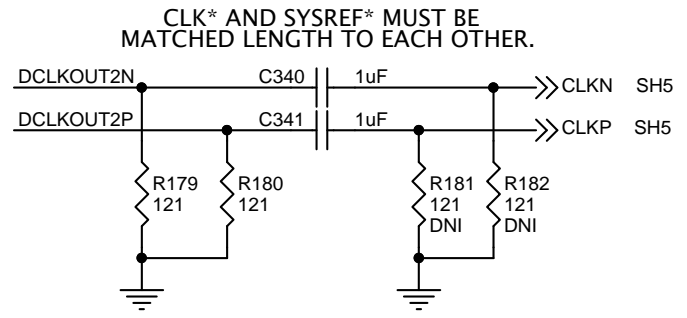
**TEXAS INSTRUMENTS**

Title: **DAC**

Size: <b>B</b>	Document Number: <b>DAC3XJ8X EVM</b>	Rev: <b>D</b>
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Date: Thursday, November 14, 2008 2 of 10





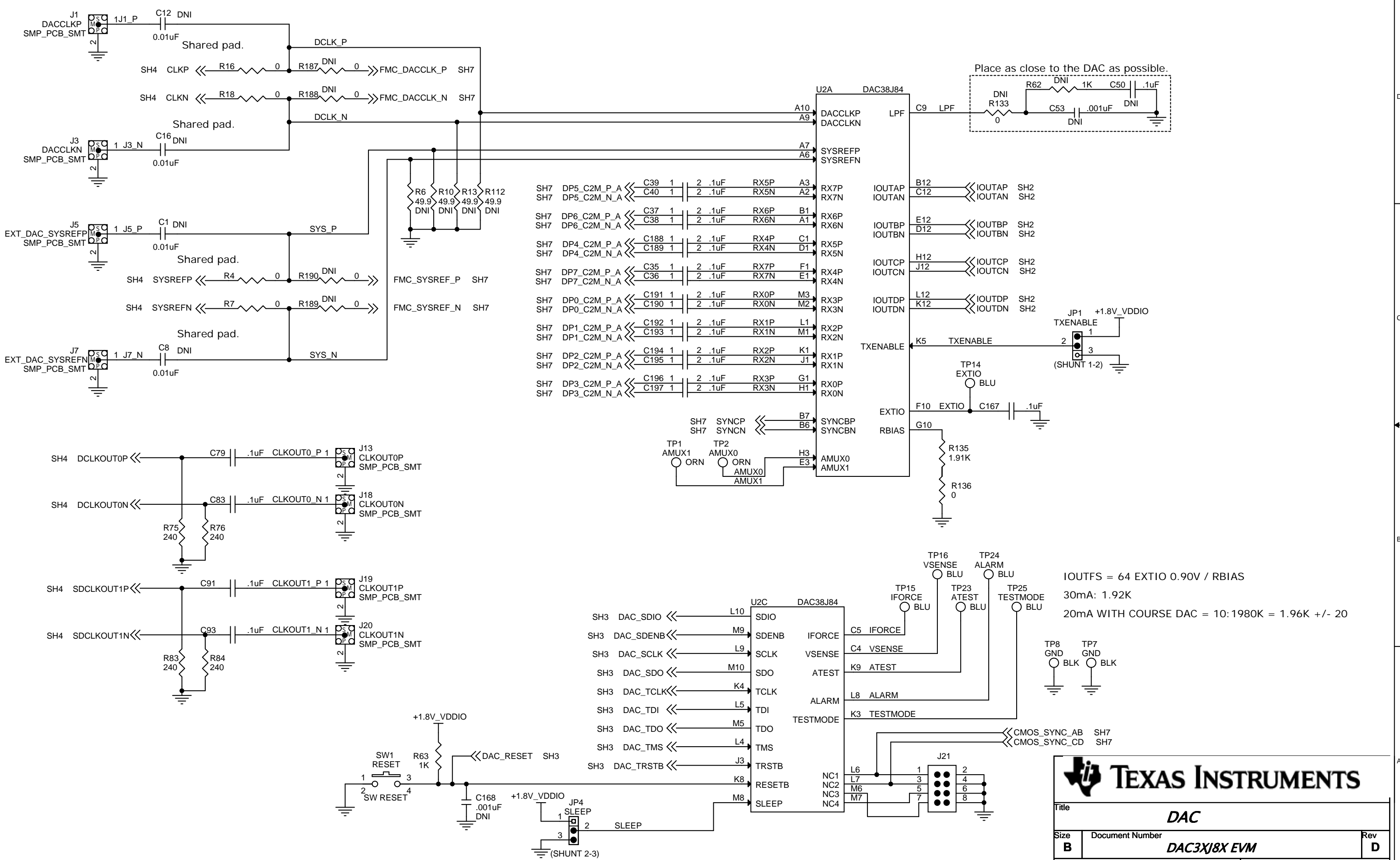
**TEXAS INSTRUMENTS**

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**CLOCK**

Size **B** Document Number **DAC3XJ8X EVM** Rev **D**

Date: Friday, November 08, 2013 Sheet 4 of 10



Place as close to the DAC as possible.

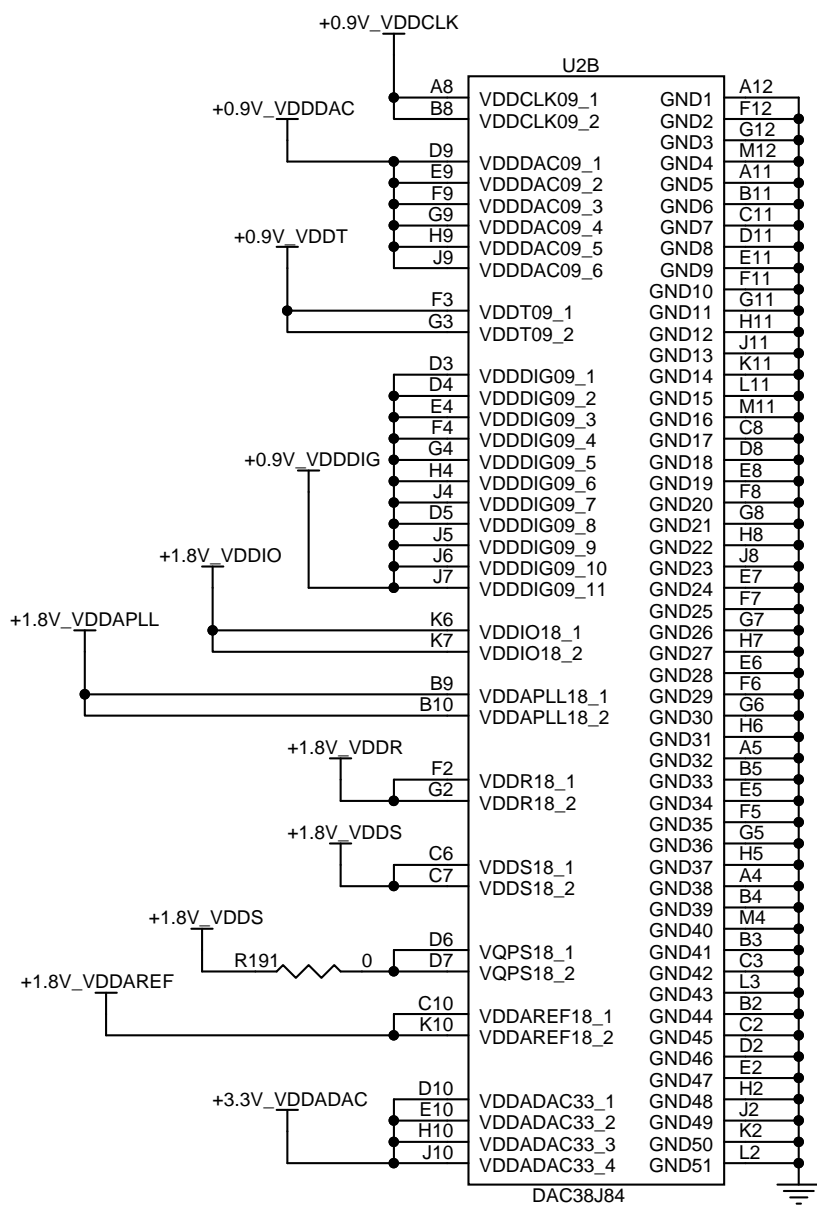
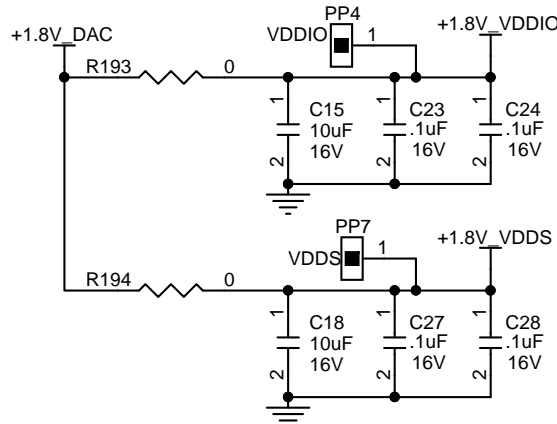
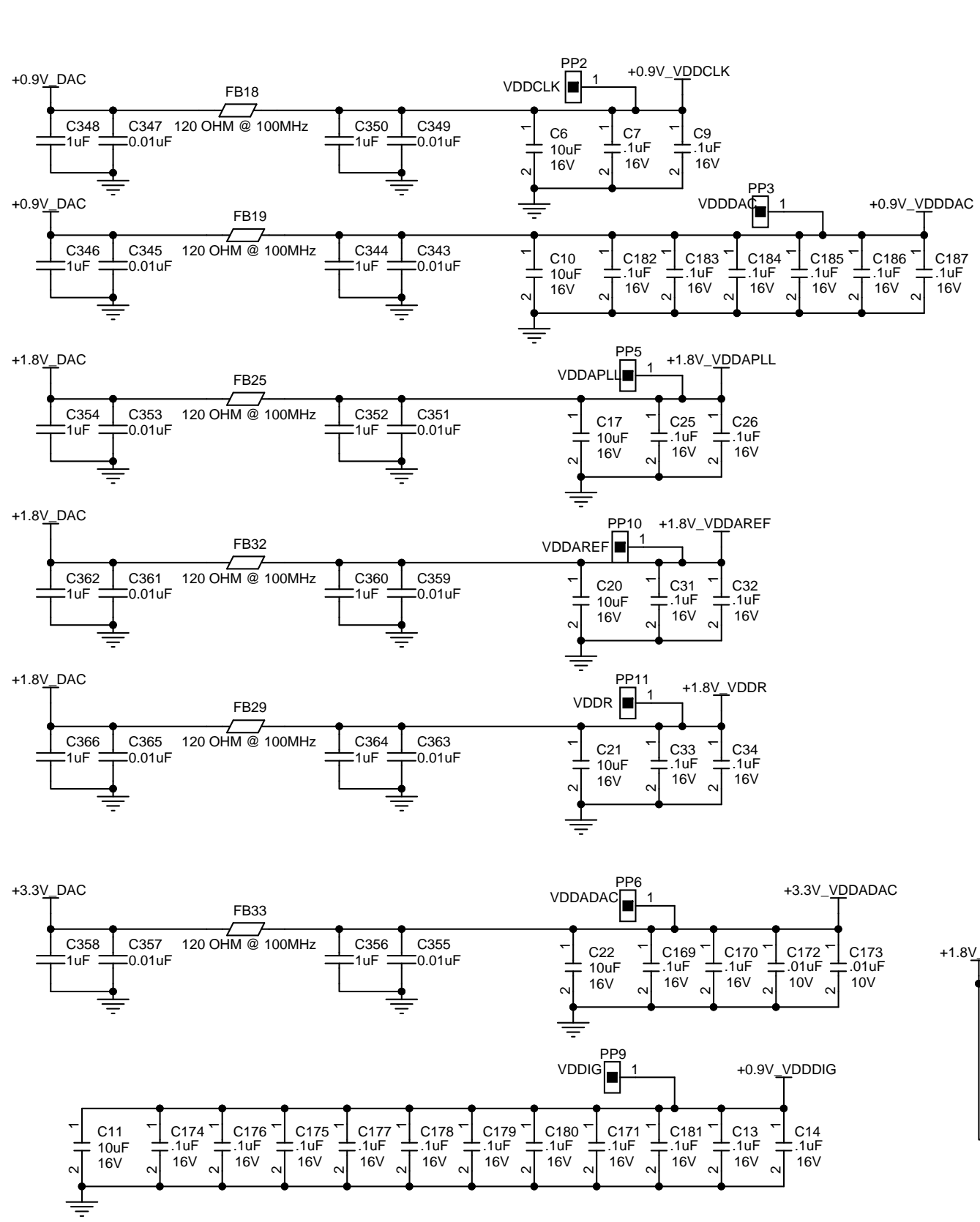
IOUTFS = 64 EXTIO 0.90V / RBIAS  
 30mA: 1.92K  
 20mA WITH COURSE DAC = 10:1980K = 1.96K +/- 20

**TEXAS INSTRUMENTS**

Title: **DAC**

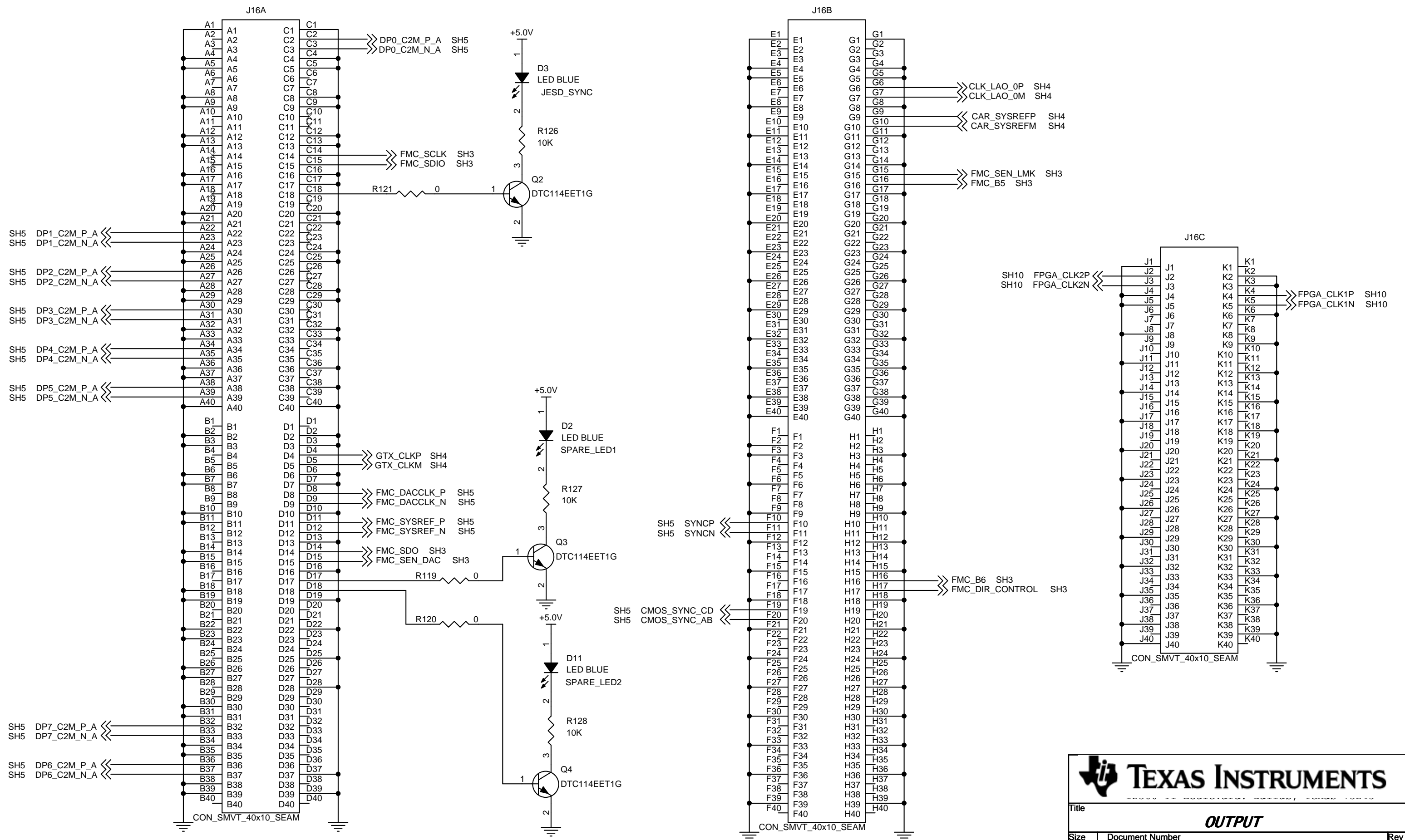
Size: **B** Document Number: **DAC3XJ8X EVM** Rev: **D**

Date: Friday, November 08, 2013 Sheet 5 of 10



**TEXAS INSTRUMENTS**  
 Title: **DAC**  
 Size: **B** | Document Number: **DAC3XJ8X EVM** | Rev: **D**  
 Date: **Friday, November 08, 2013** | Sheet: **6** of **10**

# MATES W/ XILINX FMC CONNECTOR - J22

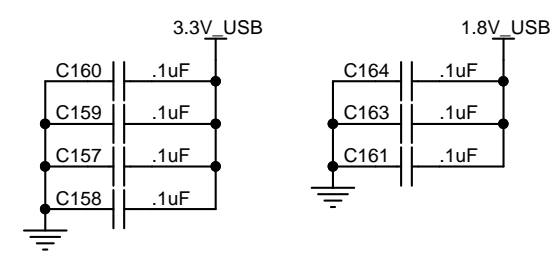
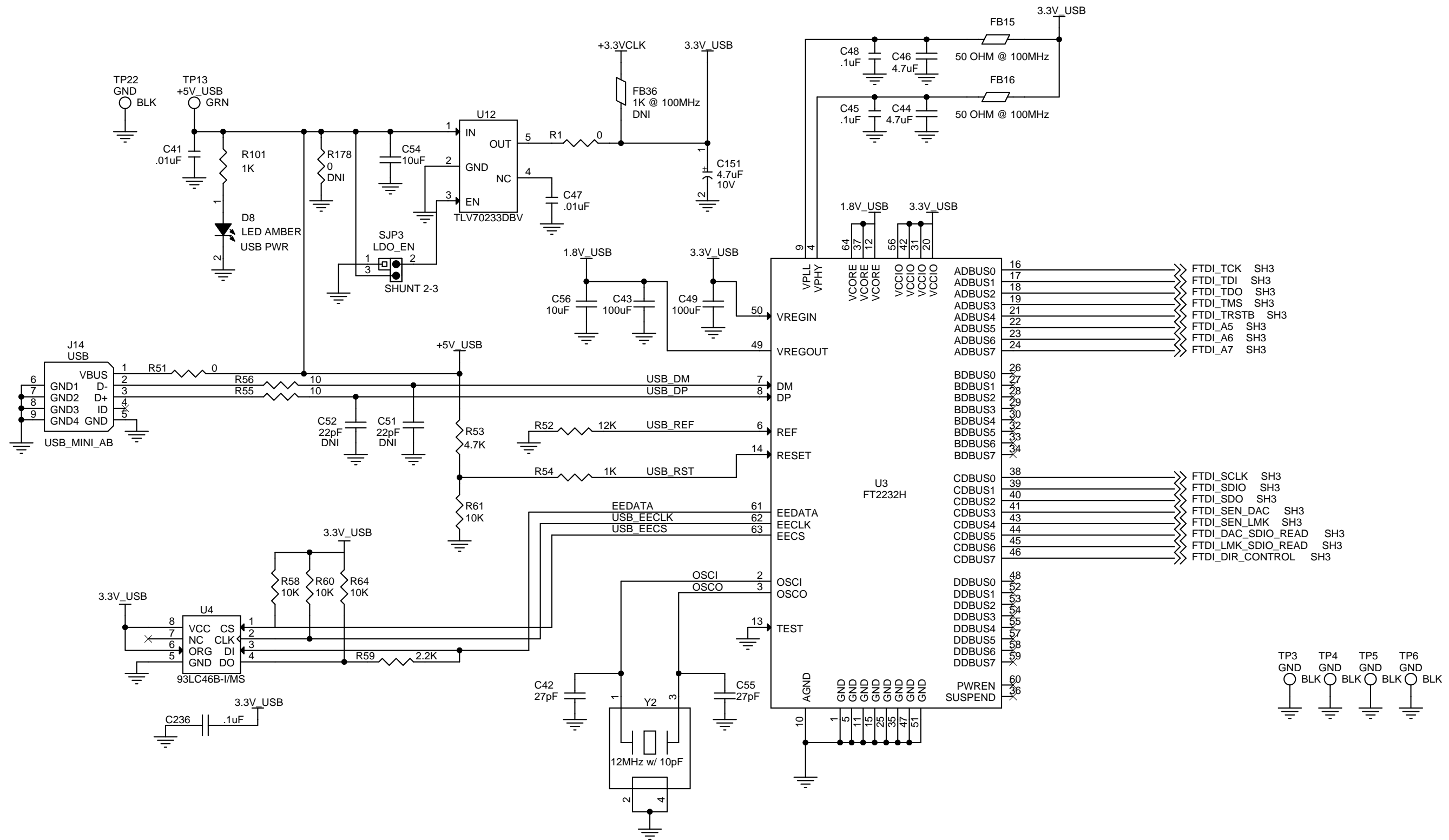


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Title: **OUTPUT**

Size: **B** | Document Number: **DAC3XJ8X EVM** | Rev: **D**

Date: **Friday, November 08, 2013** | Sheet: **7** of **10**



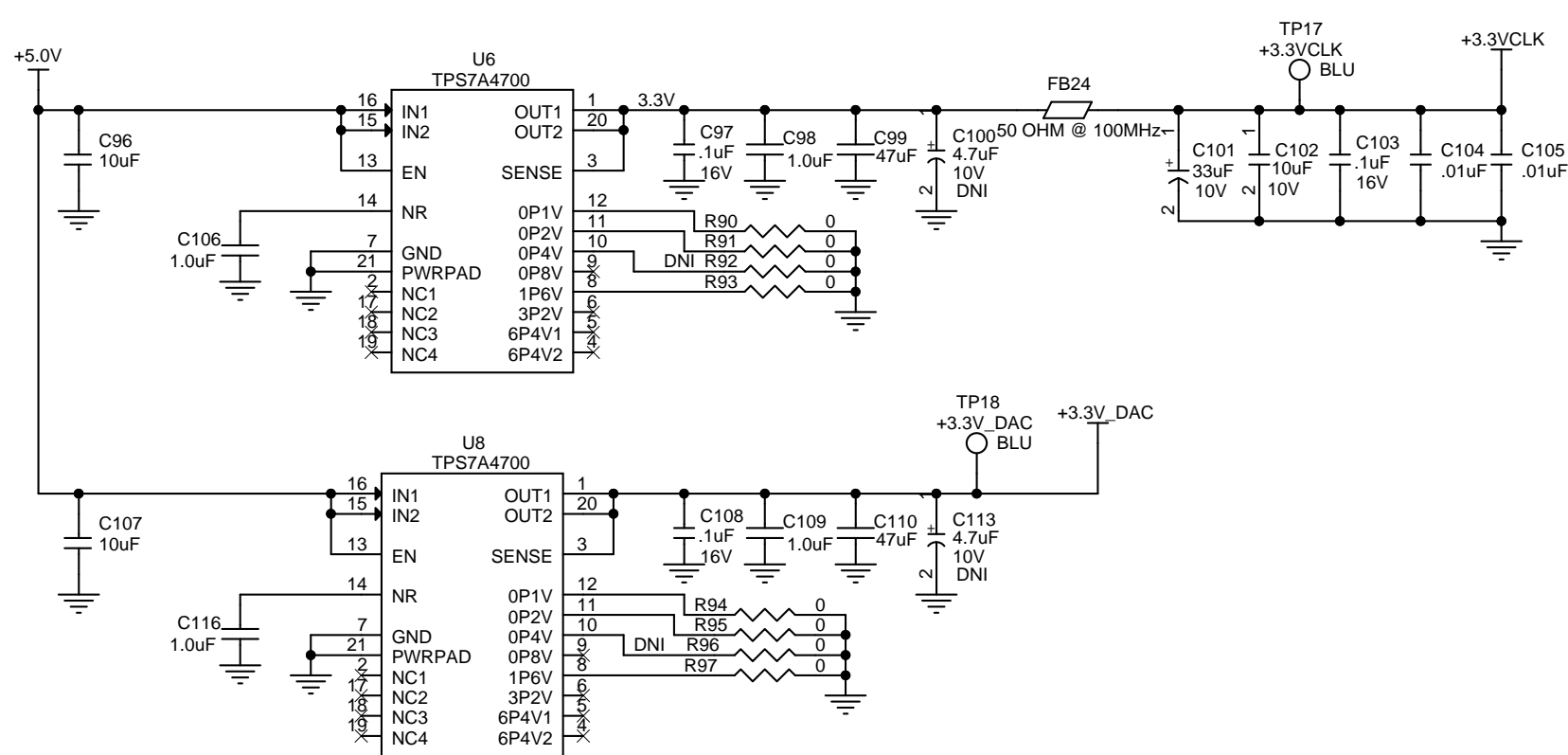
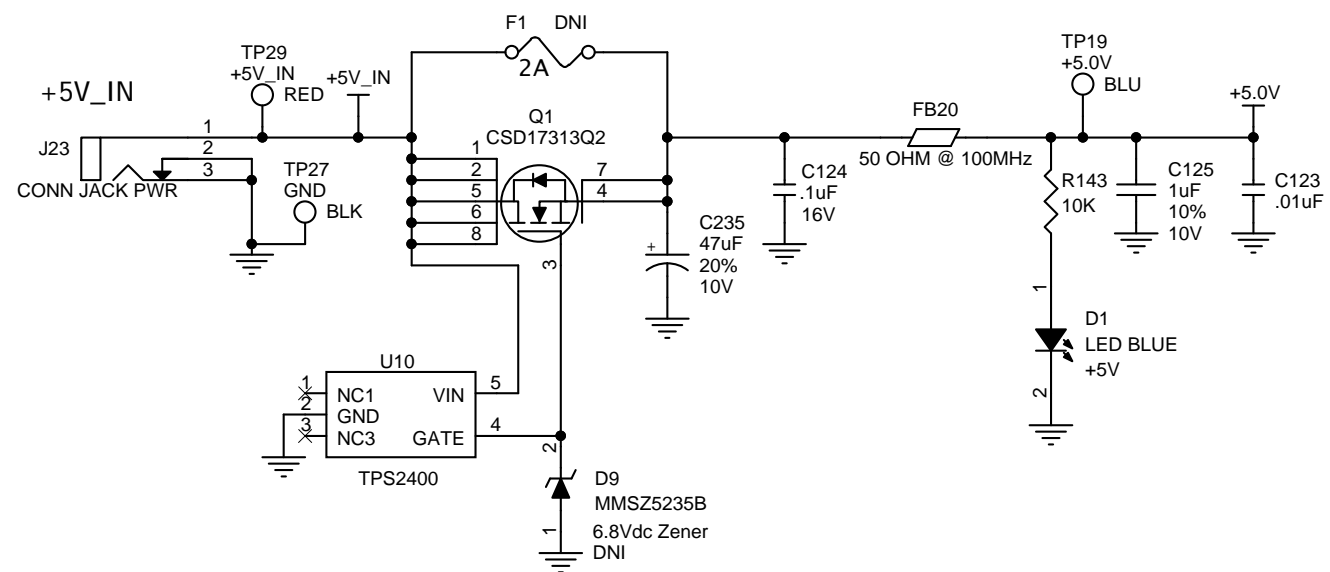
**TEXAS INSTRUMENTS**

Title: **USB INTERFACE**

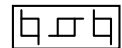
Size: **B** Document Number: **DAC3XJ8X EVM** Rev: **D**

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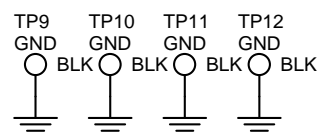




BARE BOARD, DAC38J84



- |   |                                |   |                                |
|---|--------------------------------|---|--------------------------------|
| <br>MT1<br>STANDOFF, HEX, 4-40 X 1 1/4", ALUM | <br>SCREW, PHIL, 4-40x3/4", SS | <br>MT5<br>STANDOFF, HEX, 4-40 X 1 1/4", ALUM | <br>SCREW, PHIL, 4-40x3/4", SS |
| <br>MT2<br>STANDOFF, HEX, 4-40 X 1 1/4", ALUM | <br>SCREW, PHIL, 4-40x3/4", SS | <br>MT6<br>STANDOFF, HEX, 4-40 X 1 1/4", ALUM | <br>SCREW, PHIL, 4-40x3/4", SS |
| <br>MT3<br>STANDOFF, HEX, 4-40 X 1 1/4", ALUM | <br>SCREW, PHIL, 4-40x3/4", SS | <br>MT7<br>STANDOFF, HEX, 4-40 X 1 1/4", ALUM | <br>SCREW, PHIL, 4-40x3/4", SS |
| <br>MT4<br>STANDOFF, HEX, 4-40 X 1 1/4", ALUM | <br>SCREW, PHIL, 4-40x3/4", SS | <br>MT8<br>STANDOFF, HEX, 4-40 X 1 1/4", ALUM | <br>SCREW, PHIL, 4-40x3/4", SS |



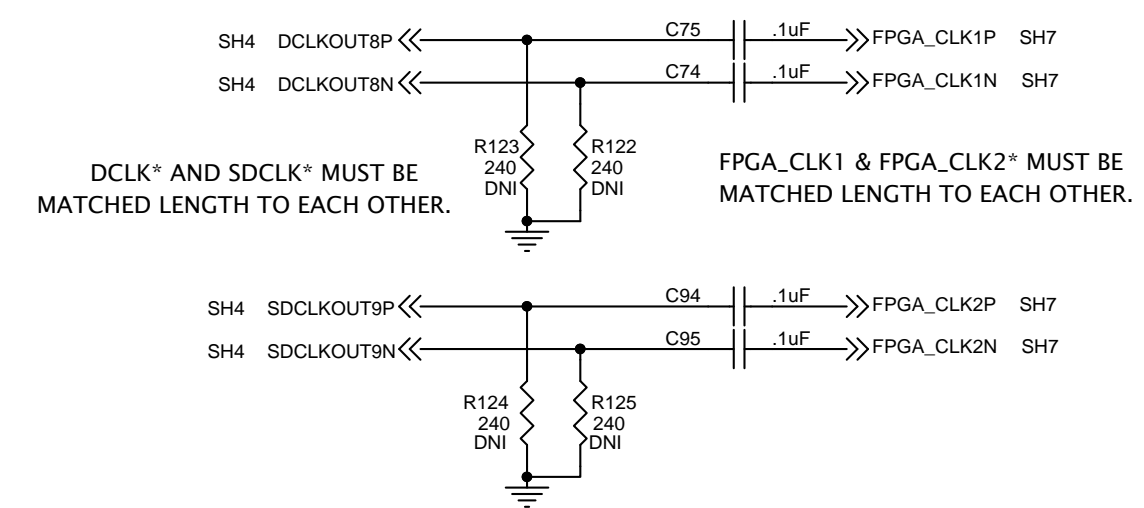
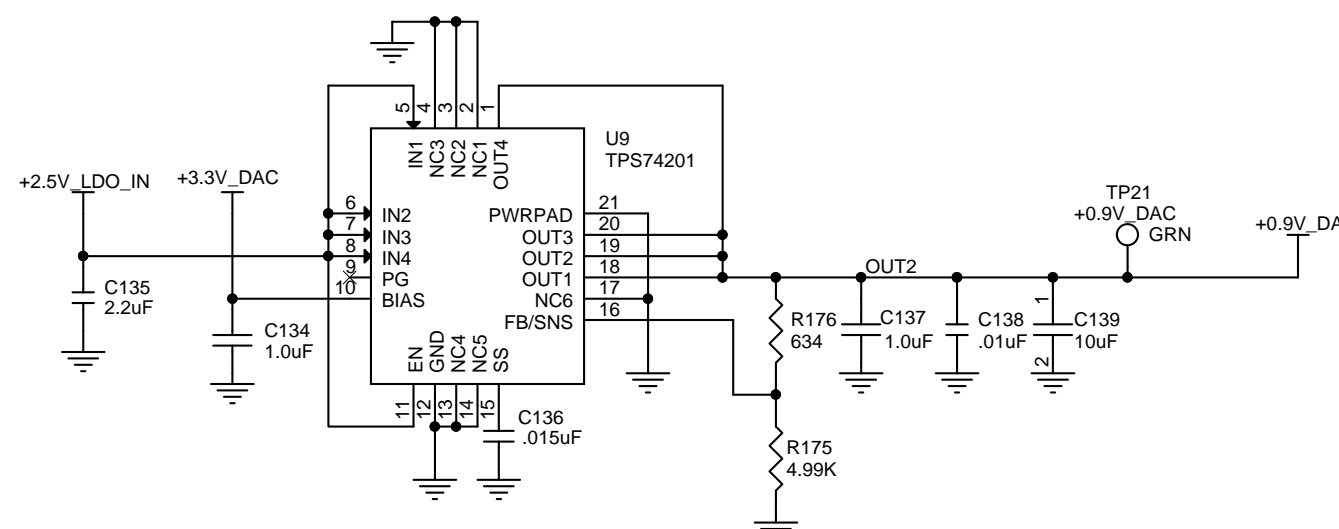
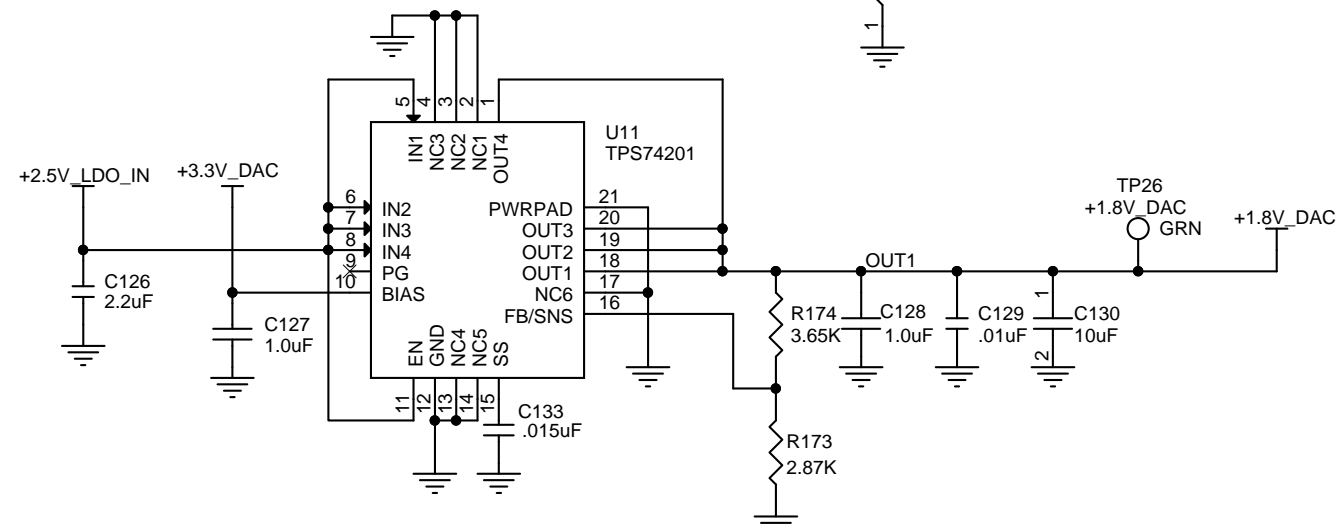
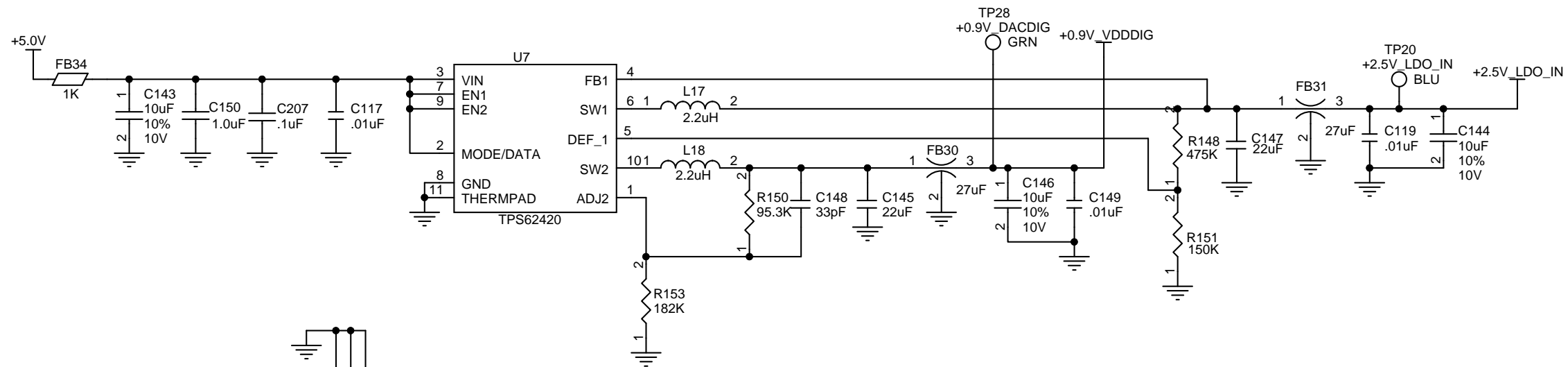
**TEXAS INSTRUMENTS**

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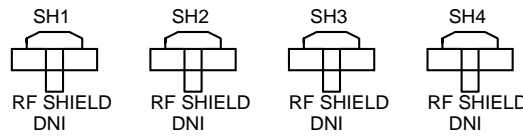
Title: **MAIN POWER**

Size B Document Number: **DAC3XJ8X EVM** Rev D

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LEADER TECH RF SHIELD P/N SL-11356



**TEXAS INSTRUMENTS**

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**MAIN POWER**

**DAC3XJ8X EVM**

Rev D

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